

## Dual N-Channel 60 V (D-S) MOSFET

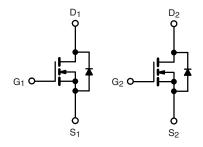
| PRODUCT SUMMARY                           |        |  |  |  |
|---|--------|--|--|--|
| V <sub>DS</sub> (V)                       | 60     |  |  |  |
| $R_{DS(on)} (\Omega)$ at $V_{GS} = 10 V$  | 0. 027 |  |  |  |
| $R_{DS(on)} (\Omega)$ at $V_{GS} = 4.5 V$ | 0. 041 |  |  |  |
| I <sub>D</sub> (A) per leg                | 8      |  |  |  |
| Configuration                             | Dual   |  |  |  |

#### FEATURES

- TrenchFET<sup>®</sup> power MOSFET
- + 100 %  $\rm R_g$  and UIS tested







N-Channel MOSFET N-Channel MOSFET

| <b>ABSOLUTE MAXIMUM RATINGS</b> ( $T_C = 25 \text{ °C}$ , unless otherwise noted) |                         |                                   |             |      |  |  |
|---|-------------------------|-----------------------------------|-------------|------|--|--|
| PARAMETER   |                         | SYMBOL                            | LIMIT       | UNIT |  |  |
| Drain-Source Voltage  |                         | V <sub>DS</sub>                   | 60          | V    |  |  |
| Gate-Source Voltage   |                         | V <sub>GS</sub>                   | ± 20        | v    |  |  |
| Continuous Drain Current  | T <sub>C</sub> = 25 °C  | I                                 | 8           |      |  |  |
| Continuous Drain Current  | T <sub>C</sub> = 125 °C | ۱ <sub>D</sub>                    | 4           |      |  |  |
| Continuous Source Current (Diode Conduction) <sup>a</sup>                         |                         | I <sub>S</sub>                    | 3.6         | А    |  |  |
| Pulsed Drain Current <sup>b</sup>   |                         | I <sub>DM</sub>                   | 50          |      |  |  |
| Single Pulse Avalanche Current  | L = 0.1 mH              | I <sub>AS</sub>                   | 18          |      |  |  |
| Single Pulse Avalanche Energy   |                         | E <sub>AS</sub>                   | 16.2        | mJ   |  |  |
| Maximum Power Dissipation <sup>b</sup>  | T <sub>C</sub> = 25 °C  | PD                                | 4           | W    |  |  |
|   | T <sub>C</sub> = 125 °C | гD                                | 1.3         | ٧V   |  |  |
| Operating Junction and Storage Temperature Range                                  | •                       | T <sub>J</sub> , T <sub>stg</sub> | -55 to +175 | °C   |  |  |

| THERMAL RESISTANCE RATINGS |                        |                   |       |      |  |
|----------------------------|------------------------|-------------------|-------|------|--|
| PARAMETER                  |                        | SYMBOL            | LIMIT | UNIT |  |
| Junction-to-Ambient        | PCB Mount <sup>c</sup> | R <sub>thJA</sub> | 110   | °C/W |  |
| Junction-to-Foot (Drain)   |                        | R <sub>thJF</sub> | 34    | 0/10 |  |

#### Notes

a. Package limited.

b. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

c. When mounted on 1" square PCB (FR4 material).

| <b>SPECIFICATIONS</b> ( $T_C = 25 \text{ °C}$ , unless otherwise noted) |                     |   |   |      |      |       |      |
|---|---------------------|---|---|------|------|-------|------|
| PARAMETER   | SYMBOL              | TEST CONDITIONS   |   | MIN. | TYP. | MAX.  | UNIT |
| Static  |                     |   |   |      |      |       |      |
| Drain-Source Breakdown Voltage  | V <sub>DS</sub>     | $V_{GS} = 0 V, I_D = 250 \mu A$   |   | 60   | -    | -     | v    |
| Gate-Source Threshold Voltage   | V <sub>GS(th)</sub> | V <sub>DS</sub> =   | = V <sub>GS</sub> , I <sub>D</sub> = 250 μA                   | 1.5  |      | 2.5   | v    |
| Gate-Source Leakage   | I <sub>GSS</sub>    | V <sub>DS</sub> =   | $V_{DS}$ = 0 V, $V_{GS}$ = ± 20 V                             |      | -    | ± 100 | nA   |
|   |                     | $V_{GS} = 0 V$  | V <sub>DS</sub> = 60 V  | -    | -    | 1     | μA   |
| Zero Gate Voltage Drain Current   | I <sub>DSS</sub>    | $V_{GS} = 0 V$  | $V_{DS} = 60 \text{ V}, \text{ T}_{J} = 125 ^{\circ}\text{C}$ | -    | -    | 50    |      |
|   |                     | $V_{GS} = 0 V$  | $V_{DS} = 60 \text{ V}, \text{ T}_{J} = 175 ^{\circ}\text{C}$ | -    | -    | 150   |      |
| On-State Drain Current <sup>a</sup>                                     | I <sub>D(on)</sub>  | $V_{GS}$ = 10 V   | $V_{DS} \ge 5 V$  | 20   | -    | -     | А    |
|   |                     | $V_{GS} = 10 \text{ V}$   | I <sub>D</sub> = 4.5 A-                                       |      |      | 0.027 |      |
| Drain-Source On-State Resistance <sup>a</sup>                           | R <sub>DS(on)</sub> | $V_{GS} = 10 V$   | I <sub>D</sub> = 4.5 A, T <sub>J</sub> = 125 °C               | -    | -    | 0.060 | Ω    |
|   | 0.000               | $V_{GS} = 10 V$   | I <sub>D</sub> = 4.5 A, T <sub>J</sub> = 175 °C               | -    | -    | 0.081 |      |
|   |                     | $V_{GS} = 4.5 V$  | $I_D = 4 A$   |      |      | 0.041 |      |
| Forward Transconductance <sup>f</sup>                                   | 9fs                 | V <sub>DS</sub>   | = 15 V, I <sub>D</sub> = 4.5 A                                | -    | 15   | -     | S    |
| Dynamic <sup>b</sup>  |                     |   |   |      |      |       |      |
| Input Capacitance   | C <sub>iss</sub>    |   | V <sub>GS</sub> = 0 V V <sub>DS</sub> = 25 V, f = 1 MHz       | -    | 600  | 750   | pF   |
| Output Capacitance  | C <sub>oss</sub>    | $V_{GS} = 0 V$  |   | -    | 110  | 140   |      |
| Reverse Transfer Capacitance  | C <sub>rss</sub>    | ]   |   | -    | 50   | 62    |      |
| Total Gate Charge <sup>c</sup>  | Qg                  |   |   | -    |      | 18    |      |
| Gate-Source Charge <sup>c</sup>   | Q <sub>gs</sub>     | $V_{GS} = 10 \text{ V}$   | $V_{DS} = 30 \text{ V}, \text{ I}_{D} = 5.3 \text{ A}$        | -    |      | 2.7   | nC   |
| Gate-Drain Charge <sup>c</sup>  | Q <sub>gd</sub>     | ]   |   | -    |      | 4.2   |      |
| Gate Resistance   | R <sub>g</sub>      |   | f = 1 MHz   | 1.3  | -    | 6     | Ω    |
| Turn-On Delay Time <sup>c</sup>   | t <sub>d(on)</sub>  |   |   |      | 7    | 11    | ns   |
| Rise Time <sup>c</sup>  | t <sub>r</sub>      | $\label{eq:VDD} \begin{array}{l} V_{\text{DD}}=30 \text{ V}, \ R_{\text{L}}=6.8 \ \Omega \\ I_{\text{D}}\cong 4.4 \ \text{A}, \ V_{\text{GEN}}=10 \ \text{V}, \ R_{g}=1 \ \Omega \end{array}$ |   | -    | 3.3  | 5     |      |
| Turn-Off Delay Time <sup>c</sup>  | t <sub>d(off)</sub> |   |   | -    | 22.4 | 33.5  |      |
| Fall Time <sup>c</sup>  | t <sub>f</sub>      |   |   | -    | 2.1  | 3.2   |      |
| Source-Drain Diode Ratings and Characteristics <sup>b</sup>             |                     |   |   |      |      |       |      |
| Pulsed Current <sup>a</sup>   | I <sub>SM</sub>     |   |   | -    | -    | 28    | А    |
| Forward Voltage   | V <sub>SD</sub>     | I <sub>F</sub> =  | = 2 A, V <sub>GS</sub> = 0 V                                  | -    | 0.75 | 1.1   | V    |

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Notes

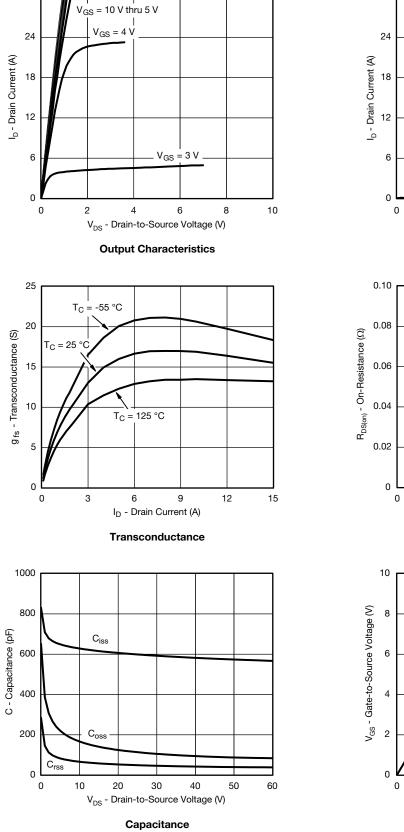
a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %. b. Guaranteed by design, not subject to production testing.

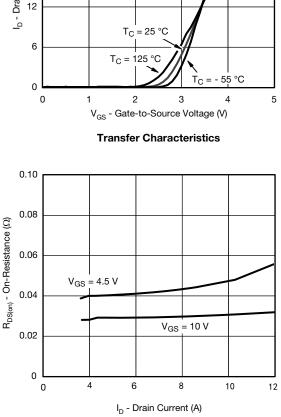
c. Independent of operating temperature.

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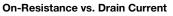


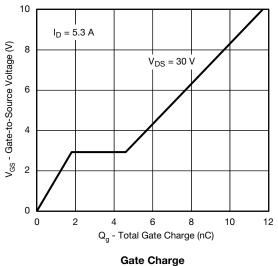
### **TYPICAL CHARACTERISTICS** ( $T_A = 25 \text{ °C}$ , unless otherwise noted)



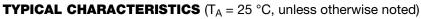


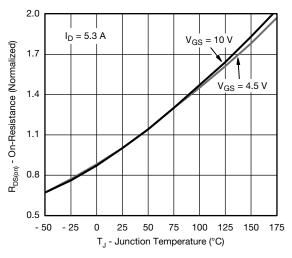
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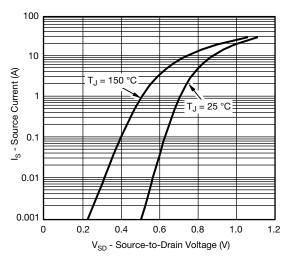




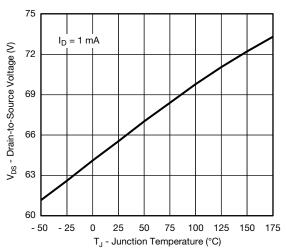




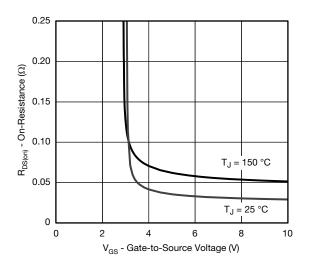
**On-Resistance vs. Junction Temperature** 



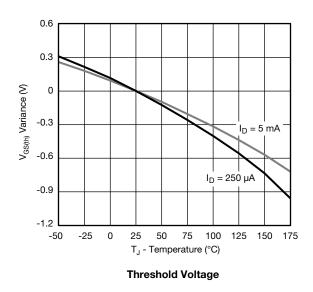
Source Drain Diode Forward Voltage



Drain Source Breakdown vs. Junction Temperature

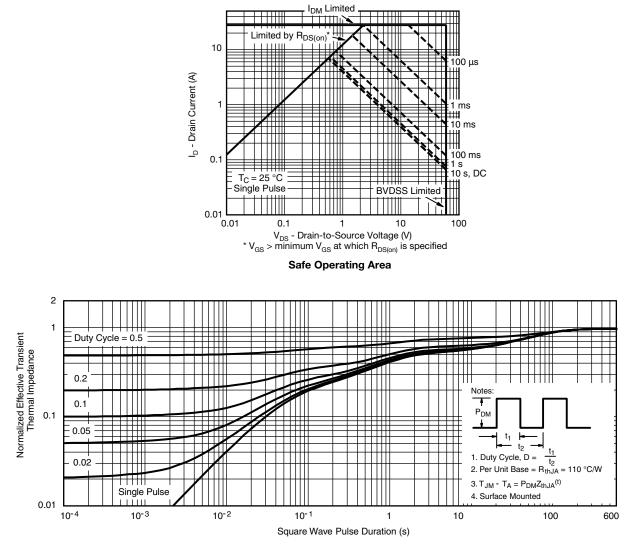


On-Resistance vs. Gate-to-Source Voltage



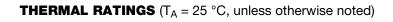


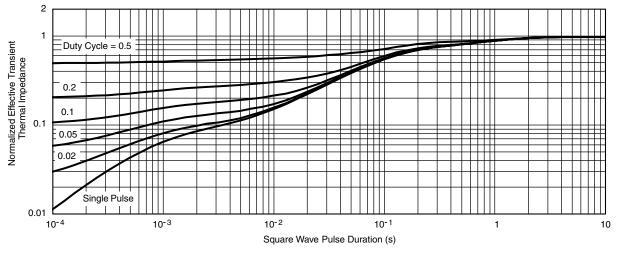
### **THERMAL RATINGS** ( $T_A = 25 \text{ °C}$ , unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



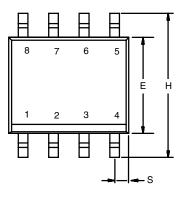


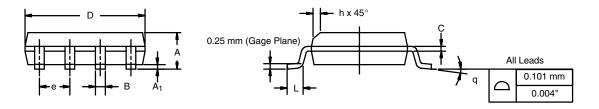


Normalized Thermal Transient Impedance, Junction-to-Foot



# SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012

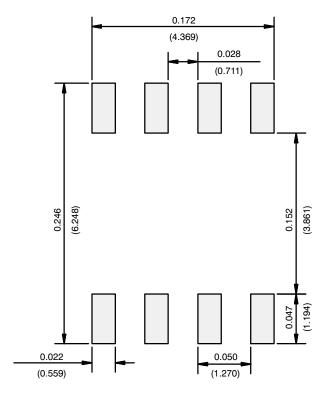




|   | MILLIM | IETERS | INC       | HES   |  |
|---|--------|--------|-----------|-------|--|
| DIM   | Min    | Мах    | Min       | Max   |  |
| A   | 1.35   | 1.75   | 0.053     | 0.069 |  |
| A <sub>1</sub>                              | 0.10   | 0.20   | 0.004     | 0.008 |  |
| В   | 0.35   | 0.51   | 0.014     | 0.020 |  |
| С   | 0.19   | 0.25   | 0.0075    | 0.010 |  |
| D   | 4.80   | 5.00   | 0.189     | 0.196 |  |
| E   | 3.80   | 4.00   | 0.150     | 0.157 |  |
| е   | 1.27   | BSC    | 0.050 BSC |       |  |
| Н   | 5.80   | 6.20   | 0.228     | 0.244 |  |
| h   | 0.25   | 0.50   | 0.010     | 0.020 |  |
| L   | 0.50   | 0.93   | 0.020     | 0.037 |  |
| q   | 0°     | 8°     | 0°        | 8°    |  |
| S   | 0.44   | 0.64   | 0.018     | 0.026 |  |
| ECN: C-06527-Rev. I, 11-Sep-06<br>DWG: 5498 |        |        |           |       |  |



### **RECOMMENDED MINIMUM PADS FOR SO-8**



Recommended Minimum Pads Dimensions in Inches/(mm)

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